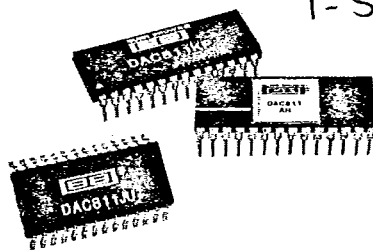


BURR-BROWN®  
**BB**



T-51-09-12  
**DAC811**

AVAILABLE IN  
DIE FORM

## Microprocessor-Compatible 12-BIT DIGITAL-TO-ANALOG CONVERTER

### FEATURES

- SINGLE INTEGRATED CIRCUIT CHIP
- MICROCOMPUTER INTERFACE: DOUBLE-BUFFERED LATCH
- VOLTAGE OUTPUT:  $\pm 10V$ ,  $\pm 5V$ ,  $+10V$
- MONOTONICITY GUARANTEED OVER TEMPERATURE
- $\pm 1/2LSB$  MAXIMUM NONLINEARITY OVER TEMPERATURE
- GUARANTEED SPECIFICATIONS AT  $\pm 12V$  AND  $\pm 15V$  SUPPLIES
- TTL/5V CMOS-COMPATIBLE LOGIC INPUTS

### DESCRIPTION

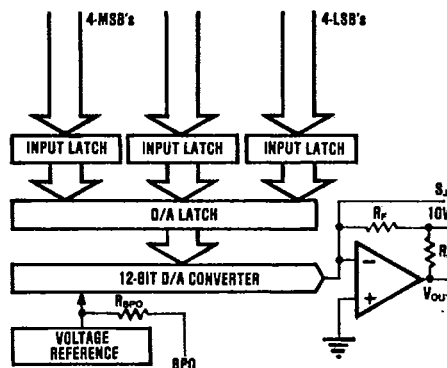
The DAC811 is a complete single-chip integrated circuit microcomputer-compatible 12-bit digital-to-analog converter. The chip includes a precision voltage reference, microcomputer interface logic, double-buffered latch, and a 12-bit D/A converter with a voltage output amplifier. Fast current switches and a laser-trimmed thin-film resistor network provide a highly accurate and fast D/A converter.

Microcomputer interfacing is facilitated by a double-buffered latch. The input latch is divided into three 4-bit nybbles to permit interfacing to 4-, 8-, 12- or 16-bit buses and to handle right- or left-justified data. The 12-bit data in the input latches is transferred to the D/A latch to hold the output value.

Input gating logic is designed so that loading the last nybble or byte of data can be accomplished simultaneously with the transfer of data (previously stored in adjacent latches) from adjacent input latches to the D/A latch. This feature avoids spurious analog output values while using an interface technique that saves computer instructions.

The DAC811 is laser trimmed at the wafer level and is specified to  $\pm 1/4LSB$  maximum linearity error (B, K, and S grades) at  $25^{\circ}C$  and  $\pm 1/2LSB$  maximum over the temperature range. All grades are guaranteed monotonic over the specification temperature range.

The DAC811 is available in six performance grades and three package types, as well as offering environmentally screened versions for enhanced reliability. DAC811J and K are specified over the temperature range of  $0^{\circ}C$  to  $+70^{\circ}C$ ; DAC811A and B are specified over  $-25^{\circ}C$  to  $+85^{\circ}C$ ; DAC811R and S are specified over  $-55^{\circ}C$  to  $+125^{\circ}C$ . DAC811J and K are packaged in a reliable 28-pin plastic DIP or plastic SOIC package, while DAC811A, B, R, and S are available in a 28-pin 0.6-inch wide dual-in-line hermetically-sealed ceramic side-brazed package (H package).



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PDS-503E

**SPECIFICATIONS**

**ELECTRICAL**

T<sub>A</sub> = +25°C. ±V<sub>CC</sub> = 12V or 15V unless otherwise noted.

MODEL	DAC811AH, JP, JU			DAC811BH, KP, KU			DAC811RH			DAC811SH			UNITS
	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
<b>INPUT</b>													
DIGITAL INPUT			12										Bits
Resolution		USB, BOB											
Digital Inputs Over Temperature Range <sup>(2)</sup>													VDC
V <sub>W</sub>	+2.0		+15										VDC
V <sub>A</sub>	0.0		+0.8										μA
I <sub>IN</sub> , V <sub>I</sub> = +2.7V			+10										μA
I <sub>IN</sub> , V <sub>I</sub> = +0.4V			±20										μA
Digital Interface Timing Over Temperature Range													nsec
t <sub>WR</sub> , WR pulse width	50												nsec
t <sub>WR1</sub> , t <sub>WR2</sub> and t <sub>LDAC</sub> valid to end of WR	50												nsec
t <sub>WR</sub> , data valid to end of WR	80												nsec
t <sub>WR</sub> , data valid hold time	0						+10						nsec
<b>TRANSFER CHARACTERISTICS</b>													
ACCURACY													LSB
Linearity Error		±1/4	±1/2		±1/8	±1/4		±1/4	±1/2		±1/8	±1/4	LSB
Differential Linearity Error		±1/2	±3/4		±1/4	±1/2		±1/2	±3/4		±1/4	±1/2	LSB
Gain Error <sup>(3)</sup>		±0.1	±0.2										%
Offset Error <sup>(3,4)</sup>		±0.05	±0.15										% of FSR <sup>(5)</sup>
Monotonicity		Guaranteed											% of FSR/±V <sub>CC</sub>
Power Supply Sensitivity, +V <sub>CC</sub>		±0.001	±0.003										% of FSR/±V <sub>CC</sub>
-V <sub>CC</sub>		±0.002	±0.006										% of FSR/±V <sub>CC</sub>
V <sub>DD</sub>		±0.0005	±0.0015										% of FSR/±V <sub>DD</sub>
DRIFT (over specification temperature range) <sup>(10)</sup>													ppm/°C
Gain		±10	±30		±10	±20		±15	±30		±15	±30	ppm of FSR/°C
Unipolar Offset		±5	±10		±5	±7		±5	±10		±5	±7	ppm of FSR/°C
Bipolar Zero		±5	±10		±5	±7		±5	±10		±5	±7	ppm of FSR/°C
Linearity Error Over Temperature Range		±1/2	±3/4		±1/4	±1/2		±1/2	±3/4		±1/4	±1/2	LSB
Monotonicity Over Temperature Range		Guaranteed											
<b>CONVERSION SPEED</b>													
SETTLING TIME <sup>(6)</sup> (to within ±0.01% of FSR of final value; 2kΩ load)													μsec
For Full Scale Range Change, 20V Range		3	4										μsec
For 1LSB Change at Major Carry <sup>(7)</sup>		3	4										μsec
Slew Rate <sup>(8)</sup>	8	12											V/μsec
<b>OUTPUT</b>													
ANALOG OUTPUT													V
Voltage Range (±V <sub>CC</sub> = 15V) <sup>(9)</sup> , Unipolar		0 to +10											V
Bipolar		±5, ±10											mA
Output Current	±5												Ω
Output Impedance (at DC)		0.2											
Short Circuit to Common Duration		Indefinite											
REFERENCE VOLTAGE													V
Voltage	+6.2	+6.3	+6.4										mA
Source Current Available for External Loads	+2.0												ppm/°C
Temperature Coefficient		±10	±30		±10	±20		±10	±30		±10	±20	
Short Circuit to Common Duration		Indefinite											
<b>POWER SUPPLY REQUIREMENTS</b>													
Voltage, +V <sub>CC</sub>	+11.4	+15	+16.5										VDC
-V <sub>CC</sub>	-11.4	-15	-16.5										VDC
V <sub>DD</sub>	+4.5	+5	+5.5										VDC
Current (no load), +V <sub>CC</sub>		+16	+25										mA
-V <sub>CC</sub>		-23	-35										mA
V <sub>DD</sub>		+8	+15										mA
Potential at DCOM with Respect to ACOM <sup>(9)</sup>			±0.5										V
Power Dissipation		625	800										mW
<b>TEMPERATURE RANGE</b>													
Specification: J, K	0		+70										°C
A, B	-25		+85										°C
R, S							-55		+125				°C
Storage: J, K	-60		+100										°C
A, B, R, S	-65		+150										°C

\*Same as specification to immediate left.

NOTES: (1) USB = Unipolar Straight Binary; BOB = Bipolar Offset Binary. (2) Refer to Logic Input Compatibility section. (3) Adjustable to zero with external trim potentiometer. (4) Error at input code 000<sub>16</sub> for both unipolar and bipolar ranges. (5) FSR means Full Scale Range and is 20V for the ±10V range. (6) Maximum represents the 3σ limit. Not 100% tested for this parameter. (7) At the major carry, 7FF<sub>16</sub> to 800<sub>16</sub> and 800<sub>16</sub> to 7FF<sub>16</sub>. (8) Minimum supply voltage required for ±10V output swing is ±13.5V. Output swing for ±11.4V supplies is at least -8V to +8V. (9) The maximum voltage at which ACOM and DCOM may be separated without affecting accuracy specifications. (10) Drift for the DAC811KU is identical to the JU grade on SOIC only, guaranteed.

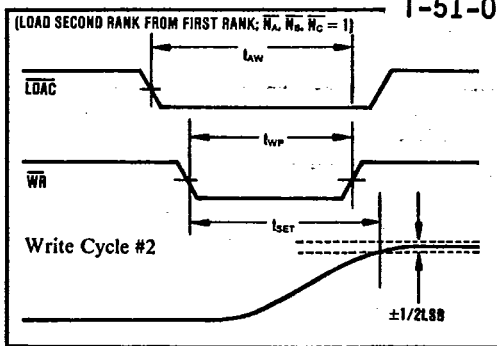
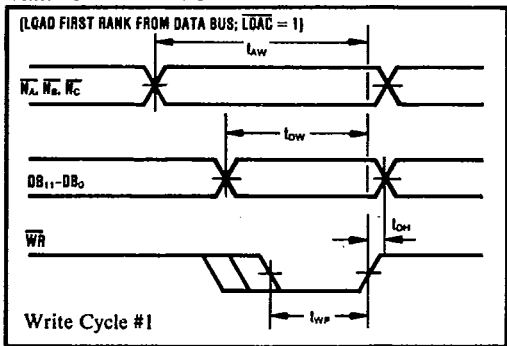
DAC811

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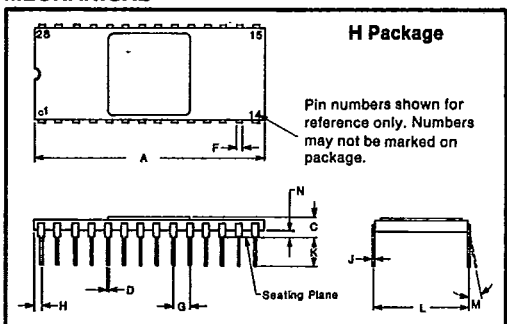
INSTRUMENTATION D/A CONVERTERS

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**TIMING DIAGRAMS**



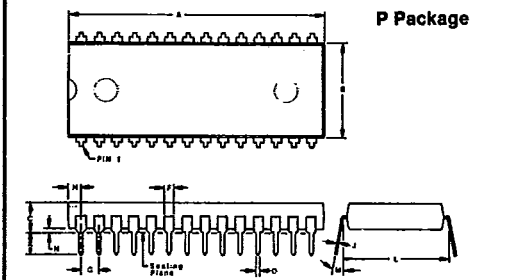
**MECHANICAL**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.386	1.414	35.20	35.92
C	.108	.166	2.74	4.22
D	.015	.021	0.38	0.53
F	.035	.060	0.89	1.52
G	.100 BASIC		2.54 BASIC	
H	.036	.064	0.91	1.63
J	.008	.012	0.20	0.30
K	.120	.240	3.05	6.10
L	.600 BASIC		15.24 BASIC	
M	—	10°	—	10°
N	.025	.060	0.64	1.52

NOTE: Leads in true position within 0.010" (0.25mm) R at MMC at seating plane.

CASE: Ceramic, hermetic  
MATING CONNECTOR: 2803MC  
WEIGHT: 4.8gm (0.17oz)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.400	1.460	35.56	37.08
B	0.530	0.575	13.48	14.61
C	0.169	0.224	4.29	5.69
D	0.015	0.023	0.38	0.58
F	0.043	0.065	1.09	1.65
G	0.100 BASIC		2.54 BASIC	
H	0.030	0.090	0.76	2.29
J	0.008	0.015	0.20	0.38
K	0.100	0.136	2.54	3.45
L	0.600 BASIC		15.24 BASIC	
M	0°C	15°C	0°C	15°C
N	0.018	0.022	0.46	0.56

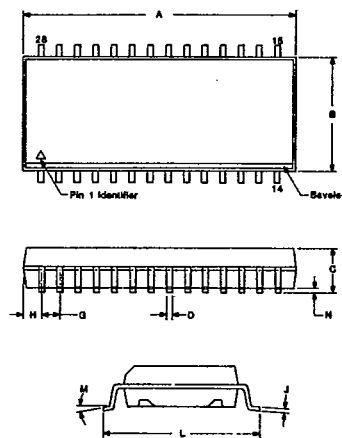
NOTE: Leads in true position within .010" (.25mm) R at MMC at seating plane.

CASE: Ceramic, hermetic  
MATING CONNECTOR: 2803MC  
WEIGHT: 4.3gm (0.15oz)

**ABSOLUTE MAXIMUM RATINGS**

+V <sub>CC</sub> .....	0 to +18V
-V <sub>CC</sub> to ACOM .....	0 to -18V
V <sub>DD</sub> to DCOM .....	0 to +7V
V <sub>DD</sub> to ACOM .....	±7V
ACOM to DCOM .....	±7V
Digital Inputs (pins 2-14, 16-19) to DCOM .....	-0.4V to +18V
External Voltage Applied to 10V Range Resistor .....	±12V
REF OUT .....	Indefinite short to ACOM
External Voltage Applied to DAC Output .....	-5 to +5V
Power Dissipation .....	1000mW
Lead Temperature, Soldering .....	+300°C, 10s
Max Junction Temperature .....	165°C
Thermal Resistance, $\theta_{JA}$ : Plastic DIP & SOIC .....	100°C/W
..... Ceramic DIP .....	65°C/W

**U Package**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.700	.716	17.78	18.19
B	.286	.302	7.28	7.67
C	.093	.109	2.36	2.77
D	.016 BASIC		0.41 BASIC	
G	.050 BASIC		1.27 BASIC	
H	.022	.038	0.56	0.97
J	.008	.012	0.20	0.30
L	.398	.414	10.11	10.52
M	5° TYP.		5° TYP.	
N	.000	.012	0.00	0.30

NOTE: Leads in true position within .010" (.25mm) R at MMC at seating plane.

Pin numbers shown for reference only. Numbers may not be marked on package.

**PIN NOMENCLATURE**

PIN	NAME	FUNCTION	PIN	NAME	FUNCTION
1	V <sub>00</sub>	Logic Supply, +5V	14	D <sub>4</sub>	DATA, Bit 5
2	WR	WRITE, command signal to load latches. Logic low loads latches.	15	DCOM	DIGITAL COMMON, V <sub>00</sub> supply return
3	LDAC	LOAD D/A CONVERTER, enables WR to load the D/A latch. Logic low enables.	16	D <sub>0</sub>	DATA, Bit 1, LSB
4	NA	NYBBLE A, enables WR to load input latch A (the most significant nybble). Logic low enables.	17	D <sub>1</sub>	DATA, Bit 2
5	NB	NYBBLE B, enables WR to load input latch B. Logic low enables.	18	D <sub>2</sub>	DATA, Bit 3
6	NC	NYBBLE C, enables WR to load input latch C (the least significant nybble). Logic low enables.	19	D <sub>3</sub>	DATA, Bit 4
7	D <sub>11</sub>	DATA, Bit 12, MSB, positive true.	20	+V <sub>CC</sub>	Analog Supply Input, +15V or +12V
8	D <sub>10</sub>	DATA, Bit 11	21	-V <sub>CC</sub>	Analog Supply Input, -15V or -12V
9	D <sub>9</sub>	DATA, Bit 10	22	GAIN ADJ	To externally adjust gain
10	D <sub>8</sub>	DATA, Bit 9	23	ACOM	ANALOG COMMON, ±V <sub>CC</sub> supply return
11	D <sub>7</sub>	DATA, Bit 8	24	V <sub>out</sub>	D/A converter voltage output
12	D <sub>6</sub>	DATA, Bit 7	25	10V RANGE	Connect to pin 24 for 10V Range
13	D <sub>5</sub>	DATA, Bit 6	26	SJ	SUMMING JUNCTION of output amplifier
			27	BPO	BIPOLAR OFFSET. Connect to pin 28 for Bipolar Operation
			28	REF OUT	6.3V reference output

**ORDERING INFORMATION**

Model	Package	Temperature Range	Linearity Error, max (+25°C)	Gain Drift (ppm/°C)
DAC811JP	Plastic DIP	0°C to +70°C	±1/2LSB	30
DAC811JU	Plastic SOIC	0°C to +70°C	±1/2LSB	30
DAC811KP	Plastic DIP	0°C to +70°C	±1/4LSB	20
DAC811KU	Plastic SOIC	0°C to +70°C	±1/4LSB	20
DAC811AH	Ceramic DIP	-25°C to +85°C	±1/2LSB	30
DAC811AH/QM	Ceramic DIP	-25°C to +85°C	±1/2LSB	30
DAC811BH	Ceramic DIP	-25°C to +85°C	±1/4LSB	20
DAC811BH/QM	Ceramic DIP	-25°C to +85°C	±1/4LSB	20
DAC811RH	Ceramic DIP	-55°C to +125°C	±1/2LSB	30
DAC811RH/QM	Ceramic DIP	-55°C to +125°C	±1/2LSB	30
DAC811SH	Ceramic DIP	-55°C to +125°C	±1/4LSB	20
DAC811SH/QM	Ceramic DIP	-55°C to +125°C	±1/4LSB	±1

**BURN-IN SCREENING OPTION**  
See text for details.

Model	Package	Temperature Range	Linearity Error, max (+25°C)	Gain Drift, (ppm/°C)
DAC811JP-BI	Plastic DIP	0°C to +70°C	±1/2LSB	30
DAC811JU-BI	Plastic SOIC	0°C to +70°C	±1/2LSB	30
DAC811KP-BI	Plastic DIP	0°C to +70°C	±1/4LSB	20
DAC811KU-BI	Plastic SOIC	0°C to +70°C	±1/4LSB	20

NOTE: (1) Or equivalent combination of time and temperature.

**DISCUSSION OF SPECIFICATIONS**

**INPUT CODES**

The DAC811 accepts positive true binary input codes. DAC811 may be connected by the user for any one of the following codes: USB (unipolar straight binary), BOB (bipolar offset binary) or, using an external inverter on the MSB line, BTC (binary two's complement). See Table I.

**LINEARITY ERROR**

Linearity Error as used in D/A converter specifications by Burr-Brown is the deviation of the analog output from a straight line drawn between the end points (inputs all "1's" and all "0's"). The DAC811 linearity error is specified at ±1/4LSB (max) at +25°C for B, K, and S grades and ±1/2LSB (max) for A, J, and R grades.

DIGITAL INPUT		ANALOG OUTPUT		
MSB	LSB	USB Unipolar Straight Binary	BOB Bipolar Offset Binary	BTC* Binary Two's Complement
1	1111111111	+Full Scale	+Full Scale	-1 LSB
0	1000000000	+1/2 Full Scale	Zero	-Full Scale
0	0111111111	1/2 Full Scale -1 LSB	-1 LSB	+Full Scale
0	0000000000	Zero	-Full Scale	Zero

\*Invert the MSB of the BOB code with external inverter to obtain BTC code.

TABLE I. Digital Input Codes.

**DIFFERENTIAL LINEARITY ERROR**

Differential Linearity Error (DLE) is the deviation from a 1LSB output change from one adjacent state to the next. A DLE specification of 1/2LSB means that the output step size can range from 1/2LSB to 3/2LSB when the input changes from one state to the next. Monotoni-

DAC811

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city requires that DLE be less than 1LSB over the temperature range of interest.

**MONOTONICITY**

A D/A converter is monotonic if the output either increases or remains the same for increasing digital inputs. All grades of DAC811 are monotonic over their specification temperature range.

**DRIFT**

Gain drift is a measure of the change in the full scale range output over the specification temperature range. Drift is expressed in parts per million per degree centigrade (ppm/°C). Gain drift is established by testing the full scale range value (e.g., +FS minus -FS) at high temperature, +25°C, and low temperature; calculating the error with respect to the +25°C value and dividing by the temperature change.

Unipolar offset drift is a measure of the change in output with all 0's on the input over the specification temperature range. Offset is measured at high temperature, +25°C, and low temperature. The maximum change in offset referred to the +25°C value divided by the temperature change is the offset drift. It is expressed in parts per million of full scale range per degree centigrade (ppm of FSR/°C).

Bipolar zero drift is measured at a digital input of 800<sub>16</sub>, the code that gives zero volts output for bipolar operation.

**SETTLING TIME**

Settling Time is the total time (including slew time) for the output to settle within an error band around its final value after a change in input. Three settling times are specified to ±0.01% of Full Scale Range (FSR): two for maximum full scale range changes of 20V and 10V, and one for a 1LSB change. The 1LSB change is measured at the major carry (7FF<sub>16</sub> to 800<sub>16</sub> and 800<sub>16</sub> to 7FF<sub>16</sub>), the input transition at which worst-case settling time occurs.

**REFERENCE SUPPLY**

DAC811 contains an on-chip 6.3V reference. This voltage (pin 28) has a tolerance of ±0.1V. The reference output may be used to drive external loads, sourcing at least 2.0mA. This current should be constant for best performance of the D/A converter.

**POWER SUPPLY SENSITIVITY**

Power Supply Sensitivity is a measure of the effect of a power supply change on the D/A converter output. It is defined as a percent of FSR output change per percent of change in either the positive, negative, or logic supply voltages about the nominal voltages. Figure 1 shows typical power supply rejection versus power supply ripple frequency.

**BURN-IN SCREENING**

Burn-in screening is an option available for the plastic-DIP and plastic-SOIC package versions of the DAC811. Burn-in duration is 160 hours at 85°C (or equivalent combination of time and temperature).

All units are tested after burn-in to ensure that grade specifications are met. To order burn-in, add "-BI" to the base model number.

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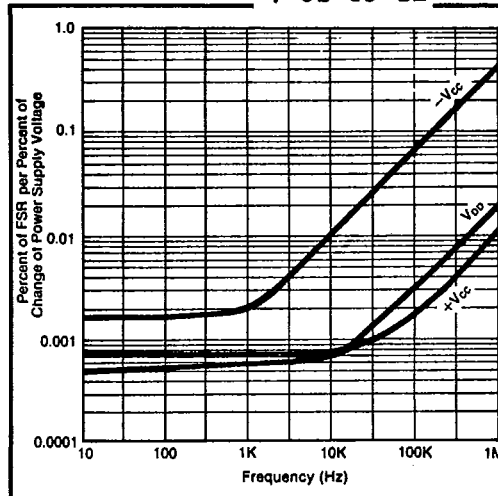


FIGURE 1. Power Supply Rejection versus Power Supply Ripple Frequency.

**/QM SCREENING**

Burr-Brown /QM models are environmentally screened versions of our ceramic-package versions of Model DAC811, designed to provide enhanced reliability. The screening, tabulated below, is performed to selected methods of MIL-STD-883. Reference to these methods provides a convenient method of communicating the screening levels and basic procedures employed; it does not imply conformance to any other military standards or to any methods of MIL-STD-883 other than those specified below. Burr-Brown's detailed procedures may vary slightly, model-to-model from those in MIL-STD-883.

**SCREENING FLOW FOR DAC811/QM**

Screen	MIL-STD-883 Method	Condition
Internal Visual	2010	B
High Temperature Storage (Stabilization Bake)	1008	C (150°C, 24Hr)
Temperature Cycling	1010	C
Burn-in	1015	B (160h at 125°C)
Constant Acceleration	2001	E
Hermeticity: Fine Leak	1014	A1 or A2
Gross Leak	1014	C
External Visual	2009	

**OPERATION**

DAC811 is a complete single IC chip 12-bit D/A converter. The chip contains a 12-bit D/A converter, voltage reference, output amplifier, and microcomputer-compatible input logic as shown in Figure 2.

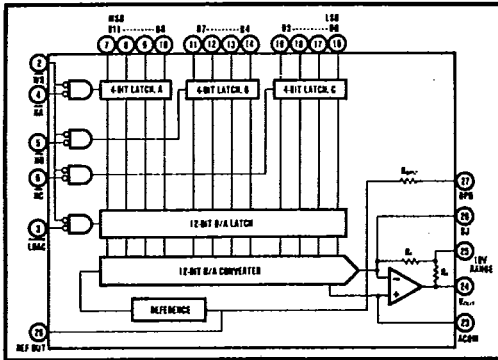


FIGURE 2. DAC811 Block Diagram.

**INTERFACE LOGIC**

Input latches A, B, and C hold data temporarily while a complete 12-bit word is assembled before loading into the D/A register. This double-buffered organization prevents the generation of spurious analog output values. Each register is independently addressable.

These input latches are controlled by  $\overline{N_A}$ ,  $\overline{N_B}$ ,  $\overline{N_C}$  and  $\overline{WR}$ .  $\overline{N_A}$ ,  $\overline{N_B}$ , and  $\overline{N_C}$  are internally NORed with  $\overline{WR}$  so that the input latches transmit data when both  $\overline{N_A}$  (or  $\overline{N_B}$ ,  $\overline{N_C}$ ) and  $\overline{WR}$  are at logic "0". When either  $\overline{N_A}$  (or  $\overline{N_B}$ ,  $\overline{N_C}$ ) or  $\overline{WR}$  go to logic "1", the input data is latched into the input registers and held until both  $\overline{N_A}$  (or  $\overline{N_B}$ ,  $\overline{N_C}$ ) and  $\overline{WR}$  go to logic "0".

The D/A latch is controlled by  $\overline{LDAC}$  and  $\overline{WR}$ .  $\overline{LDAC}$  and  $\overline{WR}$  are internally NORed so that the latches transmit data to the D/A switches when both  $\overline{LDAC}$  and  $\overline{WR}$  are at logic "0". When either  $\overline{LDAC}$  or  $\overline{WR}$  are at logic "1", the data is latched in the D/A latch and held until  $\overline{LDAC}$  and  $\overline{WR}$  go to logic "0".

All latches are level-triggered. Data present when the control signals are logic "0" will enter the latch. When any one of the control signals returns to logic "1", the data is latched. A truth table for all latches is given in Table II.

TABLE II. DAC811 Interface Logic Truth Table.

WR	$\overline{N_A}$	$\overline{N_B}$	$\overline{N_C}$	$\overline{LDAC}$	OPERATION
1	X	X	X	X	No Operation
0	0	1	1	1	Enables Input Latch 4MSB's
0	1	0	1	1	Enables Input Latch 4 Middle Bits
0	1	1	0	1	Enables Input Latch 4 LSB's
0	1	1	1	0	Loads D/A Latch From Input Latches
0	0	0	0	0	All Latches Transparent

"X" = Don't Care.

**GAIN AND OFFSET ADJUSTMENTS**

Figures 3 and 4 illustrate the relationship of Offset and Gain adjustments to unipolar and bipolar D/A converter output.

**OFFSET ADJUSTMENT**

For unipolar (USB) configurations, apply the digital input code that should produce zero voltage output and

adjust the Offset potentiometer for zero output. For bipolar (BOB, BTC) configurations, apply the digital input code that should produce the maximum negative output voltage and adjust the Offset potentiometer for minus full scale voltage. Example: If the Full Scale Range is connected for 20V, the maximum negative output voltage is -10V. See Table III for corresponding codes.

**GAIN ADJUSTMENT**

For either unipolar or bipolar configurations, apply the digital input that should give the maximum positive voltage output. Adjust the Gain potentiometer for this positive full scale voltage. See Table III for positive full scale voltages.

**±12V OPERATION**

The DAC811 is fully specified for operation on ±12V power supplies. However, in order for the output to swing to ±10V, the power supplies must be ±13.5V or greater. When operating with ±12V supplies, the output

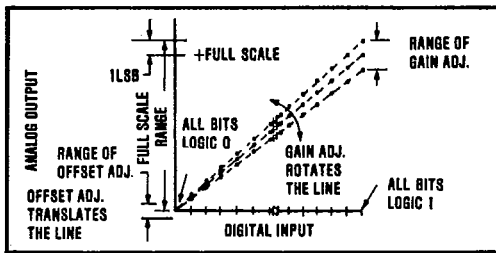


FIGURE 3. Relationship of Offset and Gain Adjustments for a Unipolar D/A Converter

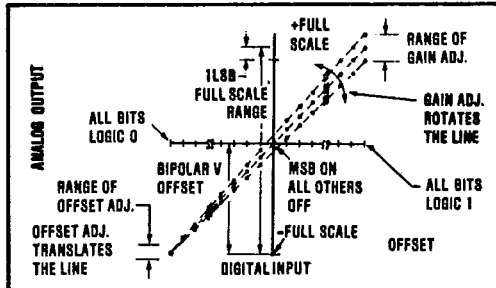


FIGURE 4. Relationship of Offset and Gain Adjustments for a Bipolar D/A Converter.

TABLE III. Digital Input/Analog Output, ±V<sub>CC</sub> = ±15V.

DIGITAL INPUT	ANALOG OUTPUT VOLTAGE		
	0 to +10V	±5V	±10V
12-Bit Resolution			
MSB			
LSB			
111111111111	+9.9976V	+4.9978V	+9.9951V
100000000000	+5.0000V	0.0000V	0.0000V
011111111111	+4.9978V	-0.0024V	-0.0049V
000000000000	0.0000V	-5.0000V	-10.0000V
1LSB	2.44mV	2.44mV	4.88mV

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swing should be restricted to  $\pm 8V$  in order to meet specifications.

**LOGIC INPUT COMPATIBILITY**

The DAC811 digital inputs are TTL, LSTTL, and 54/74HC CMOS-compatible over the operating range of  $V_{DD}$ . The input switching threshold remains at the TTL threshold over the supply range.

The logic input current over temperature is low enough to permit driving the DAC811 directly from the outputs of 4000B and 54/74C CMOS devices.

**INSTALLATION**

**POWER SUPPLY CONNECTIONS**

**Decoupling:** For optimum performance and noise rejection, power supply decoupling capacitors should be added as shown in the Connection Diagram, Figure 5.

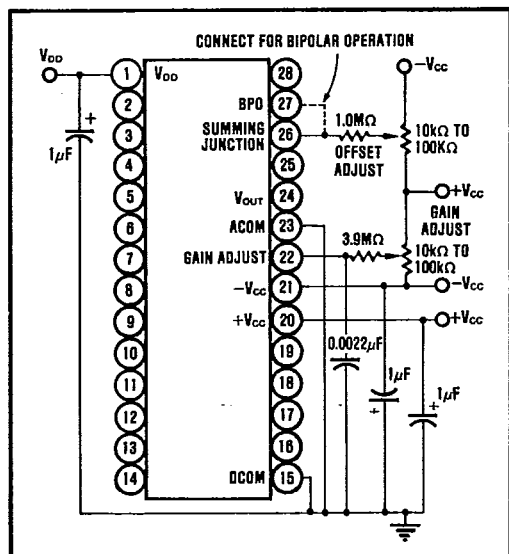


FIGURE 5. Power Supply, Gain, and Offset Potentiometer Connections.

These capacitors ( $1\mu F$  tantalum recommended) should be located close to the DAC811.

The DAC811 features separate digital and analog power supply returns to permit optimum connections for low noise and high speed performance. The Analog Common (pin 23) and Digital Common (pin 15) should be connected together at one point. Separate returns minimize current flow in low level signal paths if properly connected. Logic return currents are not added into the analog signal return path. A  $\pm 0.5V$  difference between ACOM and DCOM is permitted for specified operation. High frequency noise on DCOM with respect to ACOM may permit noise to be coupled through to the analog output, therefore, some caution is required in applying these common connections.

The Analog Common is the high quality return for the D/A converter and should be connected directly to the analog reference point of the system. The load driven by the output amplifier should be returned to the Analog Common.

**EXTERNAL OFFSET AND GAIN ADJUSTMENT**

Offset and Gain may be trimmed by installing external Offset and Gain potentiometers. Connect these potentiometers as shown in Figure 5. TCR of the potentiometers should be  $100 \text{ ppm}/^\circ\text{C}$  or less. The  $1.0M\Omega$  and  $3.9M\Omega$  resistors (20% carbon or better) should be located close to the DAC811 to prevent noise pickup. If it is not convenient to use these high value resistors, an equivalent "T" network, as shown in Figure 6, may be substituted in each case. The Gain Adjust (pin 22) is a high impedance point and a  $0.001\mu F$  to  $0.01\mu F$  ceramic capacitor should be connected from this pin to Analog Common to reduce noise pickup in all applications, including those not employing external gain adjustment.

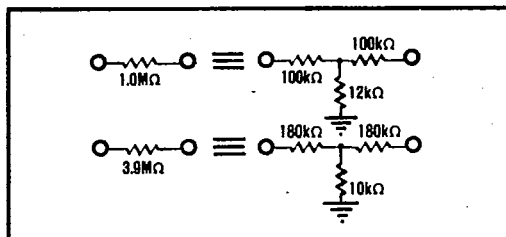


FIGURE 6. Equivalent Resistances.

**OUTPUT RANGE CONNECTIONS**

Internal scaling resistors provided in the DAC811 may be connected to produce bipolar output voltage ranges of  $\pm 10V$  and  $\pm 5V$  or unipolar output voltage range of 0 to  $+10V$ . The  $20V$  range ( $\pm 10V$  bipolar range) is internally connected. Refer to Figure 7. Connections for the output ranges are listed in Table IV.

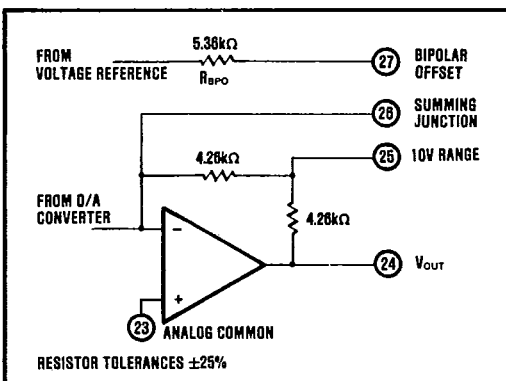


FIGURE 7. Output Amplifier Voltage Range Scaling Circuit.

Table IV. Output Range Connections.

Output Range	Digital Input Codes	Connect Pin 25 To	Connect Pin 27 To
0 to +10V	USB	24	23
±5V	BOB or BTC	24	26
±10V	BOB or BTC	NC	26

## APPLICATIONS

### MICROCOMPUTER BUS INTERFACING

The DAC811 interface logic allows easy interface micro-computer bus structures. The control signal  $\overline{WR}$  is derived from external device select logic and the I/O Write or Memory Write (depending upon the system design) signals from the microcomputer.

The latch enable lines  $\overline{N_A}$ ,  $\overline{N_B}$ ,  $\overline{N_C}$  and  $\overline{LDAC}$  determine which of the latches are enabled. It is permissible to enable two or more latches simultaneously as shown in some of the following examples.

The double-buffered latch permits data to be loaded into the input latches of several DAC811's and later strobed into the D/A latch of all D/A's simultaneously updating all analog outputs. All the interface schemes shown below use a base address decoder. If blocks of memory are unused, the base address decoder can be simplified or eliminated altogether. For instance if half the memory space is unused, address line  $A_{15}$  of the microcomputer can be used as the chip select control.

### 4-BIT INTERFACE

An interface to a 4-bit microcomputer is shown in Figure 8. Each DAC811 occupies four address locations. A 74LS139 provides the two to four decoder and selects these with the base address. Memory Write ( $\overline{WR}$ ) of the

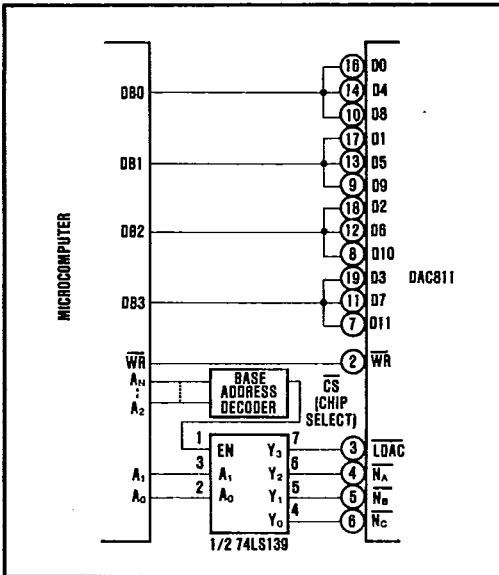


FIGURE 8. Addressing and Control for 4-Bit Microcomputer Interface.

microcomputer is connected directly to the  $\overline{WR}$  pin of the DAC811. A 8205 decoder is an alternative device to use instead of the 74LS139.

### 8-BIT INTERFACE

The control logic of DAC811 permits interfacing to right- or left-justified data formats illustrated in Figure 9. When a 12-bit D/A converter is loaded from an 8-bit

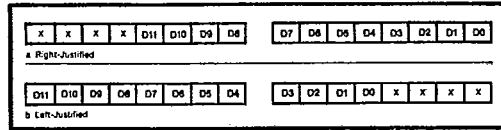


FIGURE 9. 12-Bit Data Formats for 8-Bit Systems.

bus, two bytes of data are required. Figures 10 and 11 show an addressing scheme for right-justified and left-justified data respectively. The base address is decoded from the high-order address bits.  $A_0$  and  $A_1$  address the appropriate latches. Note that adjacent addresses are used. For the right-justified case  $X10_{16}$  loads the 8 LSB's and  $X01_{16}$  loads the 4MSB's and simultaneously transfers input latch data to the D/A latch. Addresses  $X00_{16}$  and  $X11_{16}$  are not used.

Left-justified data is handled in a similar manner, shown in Figure 11. The DAC811 still occupies two adjacent locations in the microcomputer's memory map.

### INTERFACING MULTIPLE DAC811's IN 8-BIT SYSTEMS

Many applications require that the outputs of several D/A converters be updated simultaneously such as

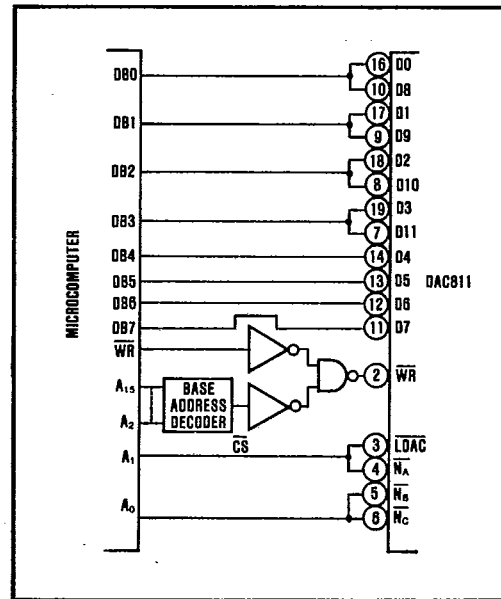


FIGURE 10. Right-Justified Data Bus Interface.

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automatic test systems. The interface shown in Figure 12 uses a 74LS138 decoder to decode a set of eight adjacent addresses to load the input latches of four DAC811's. The example shows a right-justified data format.

A ninth address using  $A_3$  causes all DAC811's to be updated simultaneously. If a particular DAC811 is always loaded last, for instance, D/A #4,  $A_3$  is not needed, thus saving 8 address spaces for other uses. Incorporate  $A_3$  into the Base Address Decoder, remove the inverter, connect the common LDAC line to  $\bar{N}_c$  of D/A #4, and connect G1 of the 74LS138 to +5V.

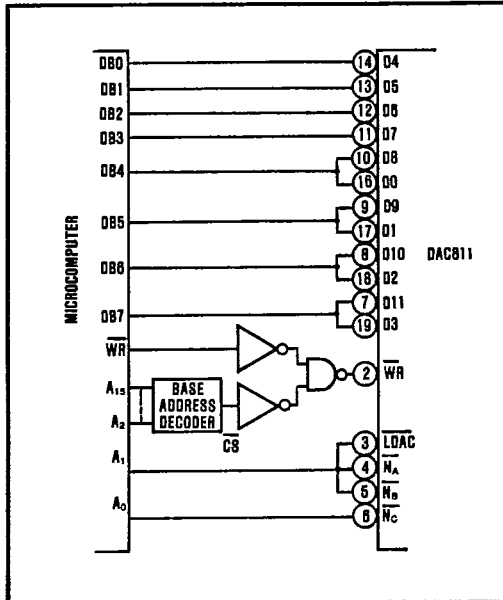


FIGURE 11. Left-Justified Data Bus Interface.

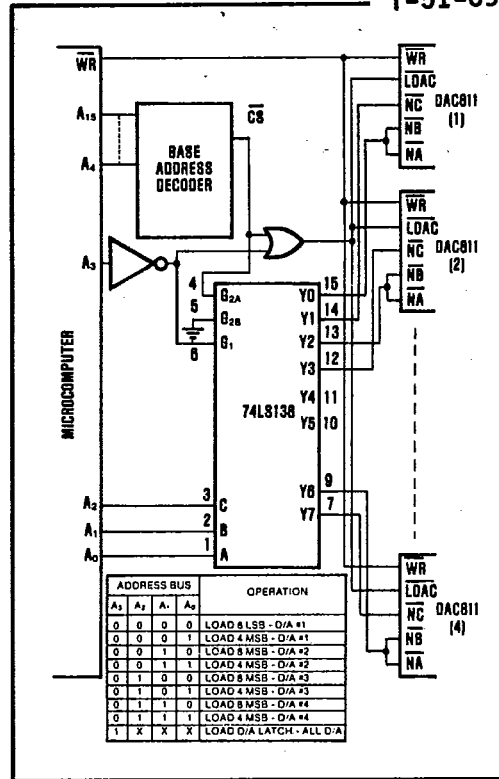


FIGURE 12. Interfacing Multiple DAC 811's to an 8-Bit Bus.

**12- AND 16-BIT MICROCOMPUTER INTERFACE**

For this application the input latch enable lines,  $\bar{N}_A$ ,  $\bar{N}_B$ ,  $\bar{N}_C$  are tied low, causing the latches to be transparent. The D/A latch, and therefore DAC 811, is selected by the address decoder and strobed by WR.